



Anniversary Feature Papers

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Deadline for manuscript
submissions:

closed (31 December 2019)

Message from the Guest Editor

Dear Colleagues,

As Editor-in-Chief of the *Journal of Manufacturing and Materials Processing*, I am pleased to announce this Special Issue, entitled "Anniversary Feature Papers". This Special Issue will be a collection of articles from Editorial Board Members and Leading Researchers discussing new knowledge or new cutting-edge developments in the science of manufacturing and materials processing.

Our goal is to provide fast dissemination of new research results and ideas, and to stimulate research groups to create new studies, innovations and knowledge without delay.

You are welcome to send a title and abstract to our Editorial Office (jmmmp@mdpi.com) for evaluation. Alternatively, you are welcome to submit full papers of your recent research outcomes within the scope of *JMMP*. All contributions will be peer-reviewed.

Prof. Dr. Steven Y. Liang
Editor-in-Chief





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Message from the Editor-in-Chief

Journal of Manufacturing and Materials Processing (JMMP) (ISSN 2504-4494) is a new MDPI peer-reviewed, open access venue with a focus on the scientific fundamentals and engineering methodologies of manufacturing and materials processing. We offer an online platform facilitating effective exchange of innovative scientific and engineering ideas and the dissemination of recent, original, and significant research and developmental findings. On behalf of the Editorial Board, I extend an invitation to our scientific and engineering colleagues to contribute high-quality, innovative, and ground-breaking research articles to *JMMP*.

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